

High-Efficiency 2A, 24V Input Synchronous Step Down Converter

Features

- Low R_{DS(ON)} or internal switches (top/bottom)
 120mΩ/75mΩ, 2.0A
- 4.5-24V input voltage range
- High-Efficiency Synchronous-Mode
- Internal soft start limits the inrush current
- Over Current protection
- Thermal shutdown
- Green package:
 TSOT23 -6 is pin compatible

Applications

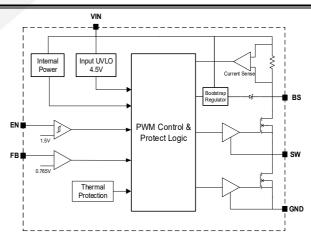
- Portable Navigation Device
- Set Top Box
- Portable TV
- LCD TV

Descriptions

The DIO6920 is high-efficiency, high frequency synchronous step-down DC-DC regulator ICs capable of delivering up to 2A output currents. The DIO6920 family operates over a wide input voltage range from 4.5V to 24V and integrate main switch and synchronous switch with very low $R_{\text{DS(ON)}}$ to minimize the conduction loss.

DIO6920 adopts the COT architecture to achieve fast transient responses for high step down applications and high efficiency at light loads. In addition, it operates at pseudo-constant frequency of 500kHz under heavy load conditions to minimize the size of inductor and capacitor.

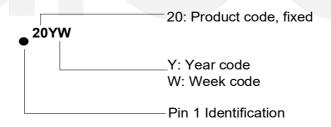
Function Block



Ordering Information

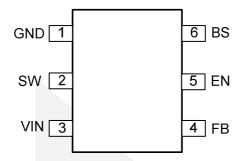
Order Part Number	Top Marking		T _A	Package	
DIO6920TST6	20YW	Green	-40 to 85°C	TSOT23-6	Tape & Reel, 3000

Marking Definition





Pin Assignments



TSOT23-6
Figure 1 Pin Assignment (Top View)

Pin Definitions

Pin Name	Description
GND	Power Ground
SW	Inductor pin. Connect this pin to the switching node of inductor.
VIN	Power Input
FB	Output Feedback Pin. Connect this pin to the center point of the output resistor divider (as shown in Figure 1) to program the output voltage: V _{OUT} =0.765*(1+R1/R2).Add optional C2 (10pF~47pF) to speed up the transient response.
EN	Enable control. Pull high to turn on. Do not float.
BS	Bootstrap. Connect a capacitor and a resistor between SW and BS pins to form a floating supply across the high-side switch driver. Recommend to use 0.1µF BS capacitor.



Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Rating" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other condition beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Pa	rameter	Rating	Unit
Supply Voltage (V+ – V-)		-0.3 to 28	V
EN Voltage		-0.3 to 28	V
FB Voltage		-0.3 to 6	V
BS Voltage		SW +6	V
CW Voltage	<10ns	-5 to 30	V
SW Voltage	>10ns	-0.3 to 28	V
Package Thermal Resistance	ӨЈА	89	°C 0.01
	θ _{JC}	44.5	°C/W
Storage Temperature Range		-65 to 150	°C
Junction Temperature Range		150	°C
Lead Temperature Range		260	°C

Recommend Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended Operating conditions are specified to ensure optimal performance to the datasheet specifications. DIOO does not Recommend exceeding them or designing to Absolute Maximum Ratings.

Parameter	Rating	Unit	
Supply Voltage	4.5 to 24	V	
Junction Temperature Range	-40 to 125	°C	
Ambient Temperature Range	-40 to 85	°C	



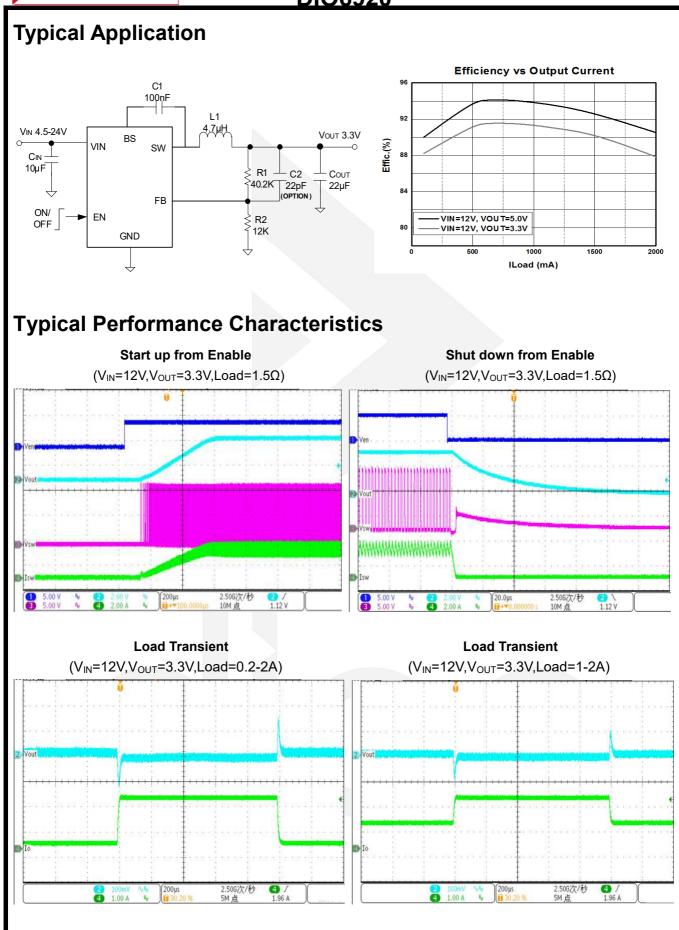
Electrical Characteristics

 V_{IN} = 12V, V_{OUT} = 1.2V, L = 2.2 μ H, C_{OUT} = 22 μ F, T_A = 25°C, I_{OUT} =1A unless otherwise specified.

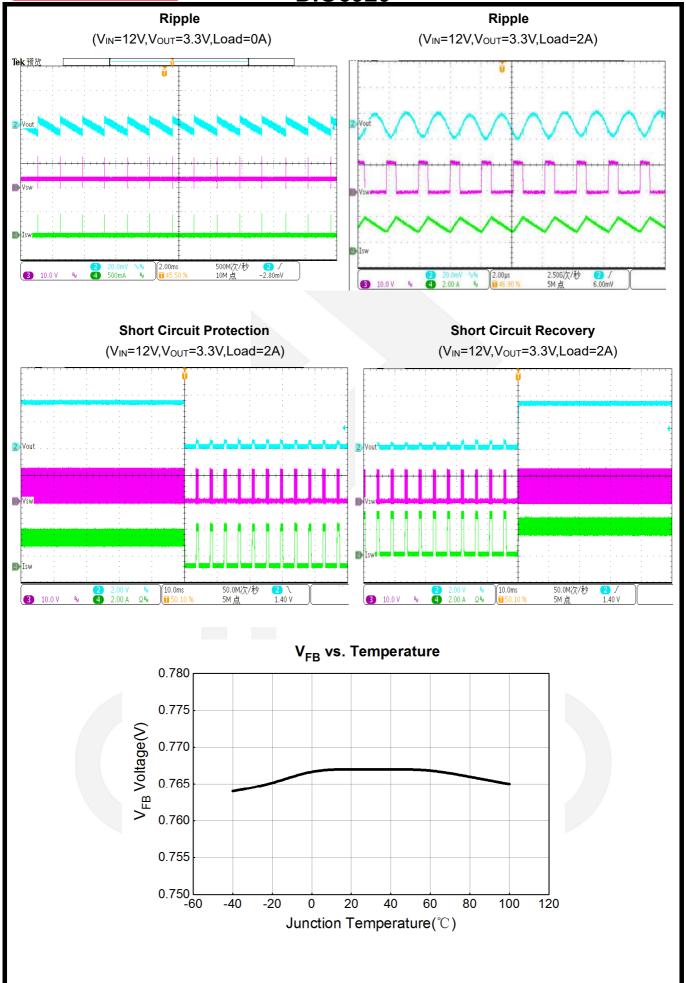
Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
V _{IN}	Input Voltage Range		4.5		24	V
IQ	Quiescent Current	I _{OUT} =0, V _{FB} =V _{REF} *105%		140		μΑ
I _{SHDN}	Shutdown Current	EN=0		5	10	μΑ
V _{REF}	Feedback Reference Voltage		0.754	0.765	0.776	V
I _{FB}	FB Input Current	V _{FB} =V _{IN}	-50		50	nA
R _{DS(ON)}	Top FET R _{ON}			120		mΩ
R _{DS(ON)}	Bottom FET Ron			75		mΩ
I _{LIM}	Bottom FET Valley Current Limit		2			А
V _{ENH}	EN Rising Threshold		1.5			V
V _{ENL}	EN Falling Threshold				0.4	V
V _{UVLO}	Input UVLO Threshold				4.5	V
f _{SW}	Switching Frequency			500		kHz
Ton	ON Time	V _{IN} = 12V, V _{OUT} = 1.2V, I _{OUT} =1A		200		ns
	Min ON Time			50		ns
	Min OFF Time			100		ns
T _{SS}	Soft Start Time			1		ms
T _{SD}	Thermal Shutdown Temperature	>		150		°C
T _{HYS}	Thermal Shutdown Hysteresis			15		°C

Specifications subject to change without notice.











Operation

DIO6920 is a synchronous buck regulator IC that integrates the COT control, top and bottom switches on the same die to minimize the switching transition loss and conduction loss. With ultra low R_{DS(ON)} power switches and proprietary COT control, this regulator IC can achieve the highest efficiency and the highest switch frequency simultaneously to minimize the external inductor and capacitor size, and thus achieving the minimum solution footprint.

DIO6920 provides protection functions such as cycle by cycle current limiting and thermal shutdown protection. DIO6920 will sense the output voltage conditions for the fault protection.

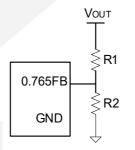
Applications Information

Because of the high integration in the DIO6920 IC, the application circuit based on this regulator IC is rather simple. Only input capacitor C_{IN} , output capacitor C_{OUT} , output inductor L and feedback resistors (R1 and R2) need to be selected for the targeted applications specifications.

Feedback resistor dividers R1 and R2

Choose R1 and R2 to program the proper output voltage. To minimize the power consumption under light loads, it is desirable to choose large resistance values for both R1 and R2. A value of between 10k and 1M is highly recommended for both resistors. If V_{OUT} is 3.3V, R1=40.2k is chosen, then R2 can be calculated to be 12k.

$$R_2 = \frac{0.765V}{V_{OUT} - 0.765V} R_1$$



Input capacitor CIN

This ripple current through input capacitor is calculated as:

$$I_{\text{CIN_RMS}} = I_{\text{OUT}} \cdot \sqrt{D(1-D)}$$

To minimize the potential noise problem, place a typical X5R or better grade ceramic capacitor really close to the IN and GND pins. Care should be taken to minimize the loop area formed by C_{IN} , and IN/GND pins. In this case, a $4.7\mu F$ low ESR ceramic capacitor is recommended.

Output capacitor Cout

The output capacitor is selected to handle the output ripple noise requirements. Both steady state ripple and transient requirements must be taken into consideration when selecting this capacitor. For the best performance, it is recommended to use X5R or better grade ceramic capacitor greater than 22µF capacitance.



Output inductor L

There are several considerations in choosing this inductor.

1) Choose the inductance to provide the desired ripple current. It is suggested to choose the ripple current to be about 40% of the maximum output current. The inductance is calculated as:

$$L = \frac{V_{OUT}(1 - V_{OUT} / V_{IN, MAX})}{F_{SW} \times I_{OUT, MAX} \times 40\%}$$

where Fsw is the switching frequency and IOUT, MAX is the maximum load current.

The DIO6920 regulator IC is quite tolerant of different ripple current amplitude. Consequently, the final choice of inductance can be slightly off the calculation value without significantly impacting the performance.

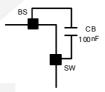
2) The saturation current rating of the inductor must be selected to be greater than the peak inductor current under full load conditions.

$$I_{SAT,MIN} > I_{OUT,MAX} + \frac{V_{OUT}(1 - V_{OUT}/V_{IN,MAX})}{2 \cdot F_{SW} \cdot L}$$

3) The DCR of the inductor and the core loss at the switching frequency must be low enough to achieve the desired efficiency requirement. It is desirable to choose an inductor with DCR<50mΩ to achieve a good overall efficiency.

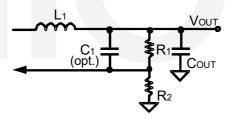
External Bootstrap Cap

This capacitor provides the gate driver voltage for internal high side MOSFET. A 100nF low ESR ceramic capacitor connected between BS pin and SW pin is recommended.



Load Transient Considerations

The DIO6920 regulator IC integrates the compensation components to achieve good stability and fast transient responses. In some applications, adding a 22pF ceramic cap in parallel with R1 may further speed up the load transient responses and is thus recommended for applications with large load transient.



Layout Design

The layout design of DIO6920 regulator is relatively simple. For the best efficiency and minimum noise problems, we should place the following components close to the IC: C_{IN}, L, R1 and R2.



- 1) It is desirable to maximize the PCB copper area connecting to GND pin to achieve the best thermal and noise performance. If the board space allowed, a ground plane is highly desirable.
- 2) C_{IN} must be close to Pins IN and GND. The loop area formed by C_{IN} and GND must be minimized.
- 3) The PCB copper area associated with SW pin must be minimized to avoid the potential noise problem.
- 4) The components R1 and R2, and the trace connecting to the FB pin must NOT be adjacent to the SW net on the PCB layout to avoid the noise problem.
- 5) If the system chip interfacing with the EN pin has a high impedance state at shutdown mode and the IN pin is connected directly to a power source such as a Li-Ion battery, it is desirable to add a pull down 1MΩ resistor between the EN and GND pins to prevent the noise from falsely turning on the regulator at shutdown mode.



CONTACT US

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